

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	25	("5757126" "5189405" "5731661" "5276414" "4633573" "6140150" "5694300" "4016643" "6566596" "6548912" "5771562") .pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 17:52
2	BRS	0	JP-361102757-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 17:58
3	BRS	2	6664624.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:00
4	BRS	0	6664624.URPN.	USPAT	2004/04/01 18:05
5	BRS	11	("4016643" "4633573" "5189405" "5276414" "5694300" "5731661" "5757126" "5771562" "6140150" "6548912" "6566596") .PN.	USPAT	2004/05/16 18:42
6	BRS	26	(semiconductor adj chip) and electrodes and (resin near4 insulating) and (metal near4 protective) and connect\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:26
7	BRS	738	(chip adj resistor) and resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:19
8	BRS	110	(semiconductor adj chip) and electrodes and (resin near4 insulating) and (metal) and (front adj (face or surface)) and ((rear or back) adj (face or surface))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:29
9	BRS	82	(chip adj resistor) and resin and electrodes and (semiconductor adj chip) and metal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:21
10	BRS	6	((semiconductor adj chip) and electrodes and (resin near4 insulating) and (metal near4 protective) and connect\$3) and ((rear or back) adj (face or surface))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:27
11	BRS	9	(chip adj resistor) and resin and electrodes and (semiconductor adj chip) and (metal near4 protect\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:22
12	BRS	38	(chip adj resistor) and resin and electrodes and (semiconductor adj chip) and (metal adj2 (layer or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:24

	Type	Hits	Search Text	DBs	Time Stamp
13	BRS	24	(chip adj resistor) and (resin near4 insulating) and electrodes and (semiconductor adj chip) and (metal adj2 (layer or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 18:58
14	BRS	379	(semiconductor adj chip) and electrodes and (resin near4 insulating) and (metal adj3 (layer or film)) and connect\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:27
15	BRS	141	((semiconductor adj chip) and electrodes and (resin near4 insulating) and (metal adj3 (layer or film)) and connect\$3) and ((rear or back) adj (face or surface))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:27
16	BRS	44	((semiconductor adj chip) and electrodes and (resin near4 insulating) and (metal adj3 (layer or film)) and connect\$3) and (front adj (face or surface)) and ((rear or back) adj (face or surface))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:38
17	BRS	4	(("5357056" "5508556" "6314637" "6005474").pn.) and resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:34
18	BRS	4	(("5357056" "5508556" "6314637" "6005474").pn.) and resin and metal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:35
19	BRS	2	(("5357056" "5508556" "6314637" "6005474").pn.) and resin and metal adj3 (layer or film)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:35
20	BRS	15	((chip adj resistor) and resin) and (front adj (face or surface)) with connect\$3 with ((rear or back) adj (face or surface))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:39
21	BRS	21	((semiconductor adj chip) and electrodes and (resin near4 insulating) and (metal adj3 (layer or film)) and connect\$3) and (front adj (face or surface)) with connect\$3 with ((rear or back) adj (face or surface))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:41
22	BRS	2469	438/106.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 19:05
23	BRS	938	438/108.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 19:05

	Type	Hits	Search Text	DBs	Time Stamp
24	BRS	750	438/125.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 19:05
25	BRS	702	438/126.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 19:05
26	BRS	975	438/127.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 19:05
27	BRS	13	(chip adj resistor) and (resin near4 insulating) same electrodes and (semiconductor adj chip) and (metal adj2 (layer or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 19:08
28	BRS	27	(chip adj resistor) and (resin near4 insulating) same electrodes and (metal adj2 (layer or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 18:36
29	BRS	495	(resin near4 insulating) same electrodes and (metal adj2 (layer or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 18:35
30	BRS	197	(resin near4 insulating) same pads and (metal adj2 (layer or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 18:35
31	BRS	21	(chip adj resistor) and (resin near4 insulating) same electrodes and (metal adj2 (layer or film)) and (via or hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 18:46
32	BRS	389	(resin near4 insulating) same electrodes and (metal adj2 (layer or film)) and (via or hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 18:35
33	BRS	163	(resin near4 insulating) same pads and (metal adj2 (layer or film)) and (via or hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 18:35
34	BRS	8	(chip adj resistor) and (resin near4 insulating) same electrodes and (semiconductor adj chip) and (metal adj2 (layer or film)) and (via or hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 18:36
35	BRS	11	(chip adj resistor) and (resin near4 insulating) same pads and (semiconductor adj chip) and (metal adj2 (layer or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 18:37
36	BRS	12	(chip adj resistor) and (resin near4 insulating) same pads and (metal adj2 (layer or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 18:38

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37	BRS	0	("4016643" "4633573" "5189405" "5276414" "5694300" "5731661" "5757126" "5771562" "6140150" "6548912" "6566596").PN. and (chip adj resistor)	USPAT	2004/05/16 18:43
38	BRS	93	(chip adj resistor) and electrodes and (metal adj2 (layer or film)) and (via or hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 18:47
39	BRS	75	((chip adj resistor) and electrodes and (metal adj2 (layer or film)) and (via or hole)) and resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 18:47
40	BRS	3	fringe adj metal and (resin near4 insulating) and electrodes and (semiconductor adj chip) and (metal adj2 (layer or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 18:59
41	BRS	100	(resin near4 insulating) same electrodes and (semiconductor adj chip) and (metal adj2 (layer or film)) and (via or hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 19:09
42	BRS	70	(resin near4 insulating) with electrodes and (semiconductor adj chip) and (metal adj2 (layer or film)) and (via or hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 19:09
43	BRS	85	(resin near4 insulating) with electrodes and substrate and resin same (metal adj2 (layer or film)) and (via or hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 19:19
44	BRS	8	("5357056" "5508556" "6314637" "6005474").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 19:12
45	BRS	13	(resin near4 insulating) with electrodes and substrate and resin same (metal adj2 (layer or film)) and (via or hole) and (chip near3 package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/16 19:19